National Semiconductor

ADC0801/ADC0802/ADC0803/ADC0804/ADC0805 8-Bit µP Compatible A/D Converters

General Description

The ADC0801, ADC0802, ADC0803, ADC0804 and ADC0805 are CMOS 8-bit successive approximation A/D converters that use a differential potentiometric laddersimilar to the 256R products. These converters are designed to allow operation with the NSC800 and INS8080A derivative control bus with TRI-STATE® output latches directly driving the data bus. These A/Ds appear like memory locations or I/O ports to the microprocessor and no interfacing logic is needed.

Differential analog voltage inputs allow increasing the common-mode rejection and offsetting the analog zero input voltage value. In addition, the voltage reference input can be adjusted to allow encoding any smaller analog voltage span to the full 8 bits of resolution.

Features

- Compatible with 8080 µP derivatives—no interfacing logic needed - access time - 135 ns
- Easy interface to all microprocessors, or operates "stand alone"

- Differential analog voltage inputs
- Logic inputs and outputs meet both MOS and TTL voltage level specifications
- Works with 2.5V (LM336) voltage reference .
- On-chip clock generator
- . 0V to 5V analog input voltage range with single 5V supply
- No zero adjust required
- 0.3" standard width 20-pin DIP package
- 20-pin molded chip carrier or small outline package
- Operates ratiometrically or with 5 V_{DC}, 2.5 V_{DC}, or ana-log span adjusted voltage reference

Kev Specifications

- Resolution
- Total error

- 8 bits
- \pm 1/4 LSB, \pm 1/2 LSB and \pm 1 LSB 100 µs
- Conversion time



	— , r			:
NSC800.	čsO Ř⊡O		Part Number	Full- Scale Adjuste
8080, Z80,	₩R O	A/D	ADC0801	± 1/4 LSE
8048, ETC.	04 −−−−− ī	NTR	ADC0802	
	1		ADC0803	± 1/2 LSE
			ADC0804	
	L		ADC0805	
		TL/H/5671-31	<u> </u>	

Error Specification (Includes Full-Scale, Zero Error, and Non-Linearity)								
Part Number	Full- Scale Adjusted	V _{REF} /2=2.500 V _{DC} (No Adjustments)	V _{REF} /2=No Connection (No Adjustments)					
ADC0801	±1/4 LSB							
ADC0802		±1/2 LSB						
ADC0803	±½ LSB							
ADC0804		±1LSB						
ADC0805			±1LSB					

Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

6.5V
-0.3V to +18V
-0.3V to (V _{CC} + 0.3V)
260°C
300°C
215°C
220°C

Electrical Characteristics

Storage Temperature Range -65° C to $+150^{\circ}$ CPackage Dissipation at TA = 25^{\circ}C875 mWESD Susceptibility (Note 10)800V

Operating Ratings (Notes 1 & 2)

Temperature Range	T _{MIN} ≤T _A ≤T _{MAX}
ADC0801/02LJ	−55°C≤T _A ≤+125°C
ADC0801/02/03/04LCJ	−40°C≤T _A ≤+85°C
ADC0801/02/03/05LCN	-40°C≤T _A ≤+85°C
ADC0804LCN	0°C≤T _A ≤+70°C
ADC0802/03/04LCV	0°C≤T _A ≤+70°C
ADC0802/03/04LCWM	0°C≤T _A ≤+70°C
Range of V _{CC}	4.5 V_{DC} to 6.3 V_{DC}

The following specifications apply for V_{CC}=5 V_{DC}, $T_{MIN} \le T_A \le T_{MAX}$ and $f_{CLK} = 640$ kHz unless otherwise specified.

Parameter	Conditions	Min	Тур	Max	Units
ADC0801: Total Adjusted Error (Note 8)	With Full-Scale Adj. (See Section 2.5.2)			± 1⁄4	LSB
ADC0802: Total Unadjusted Error (Note 8)	V _{REF} /2=2.500 V _{DC}			± 1/2	LSB
ADC0803: Total Adjusted Error (Note 8)	With Full-Scale Adj. (See Section 2.5.2)			± 1/2	LSB
ADC0804: Total Unadjusted Error (Note 8)	V _{REF} /2=2.500 V _{DC}			±1	LSB
ADC0805: Total Unadjusted Error (Note 8)	V _{REF} /2-No Connection			±1	LSB
V _{REF} /2 Input Resistance (Pin 9)	ADC0801/02/03/05 ADC0804 (Note 9)	2.5 0.75	8.0 1.1		kΩ kΩ
Analog Input Voltage Range	(Note 4) V(+) or V(-)	Gnd-0.05		V _{CC} +0.05	V _{DC}
DC Common-Mode Error	Over Analog Input Voltage Range		± 1/16	± 1/8	LSB
Power Supply Sensitivity	$V_{CC} = 5 V_{DC} \pm 10\%$ Over Allowed $V_{IN}(+)$ and $V_{IN}(-)$ Voltage Range (Note 4)		± 1/16	± 1/8	LSB

AC Electrical Characteristics

The following specifications apply for V_{CC} = 5 V_{DC} and T_A = 25°C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
т _с	Conversion Time	f _{CLK} =640 kHz (Note 6)	103		114	μs
T _C	Conversion Time	(Note 5, 6)	66		73	1/f _{CLk}
fCLK	Clock Frequency Clock Duty Cycle	V _{CC} =5V, (Note 5) (Note 5)	100 40	640	1460 60	kHz %
CR	Conversion Rate in Free-Running Mode	$\frac{\text{INTR tied to WR}}{\text{CS}=0 \text{ V}_{\text{DC}}, \text{ f}_{\text{CLK}}=640 \text{ kHz}}$	8770		9708	conv/s
tw(WR)L	Width of WR Input (Start Pulse Width)	$\overline{CS} = 0 V_{DC}$ (Note 7)	100			ns
tACC	Access Time (Delay from Falling Edge of RD to Output Data Valid)	C _L = 100 pF		135	200	ns
t _{1H} , t _{0H}	TRI-STATE Control (Delay from Rising Edge of RD to Hi-Z State)	C _L = 10 pF, R _L = 10k (See TRI-STATE Test Circuits)		125	200	ns
t _{WI} , t _{RI}	Delay from Falling Edge of WR or RD to Reset of INTR			300	450	ns
C _{IN}	Input Capacitance of Logic Control Inputs			5	7.5	pF
COUT	TRI-STATE Output Capacitance (Data Buffers)			5	7.5	pF
CONTROL	INPUTS [Note: CLK IN (Pin 4) is the input	of a Schmitt trigger circuit and is t	herefore sp	ecified se	parately]	
V _{IN} (1)	Logical "1" Input Voltage (Except Pin 4 CLK IN)	V _{CC} =5.25 V _{DC}	2.0		15	V _{DC}

		δV_{DC} and $T_{MIN} \leq T_A \leq T_{MAX}$, unles	<u> </u>	· · · ·		
Symbol	Parameter	Conditions	Min	Тур	Max	Units
CONTROL	ſ	input of a Schmitt trigger circuit and	is therefor	e specified se	parately]	
V _{IN} (0)	Logical "0" Input Voltage (Except Pin 4 CLK IN)	$V_{CC} = 4.75 V_{DC}$	_		0.8	V _{DC}
l _{IN} (1)	Logical "1" Input Current (All Inputs)	$V_{IN} = 5 V_{DC}$		0.005	1	μΑ _{DC}
I _{IN} (0)	Logical "0" Input Current (All Inputs)	V _{IN} =0V _{DC}	-1	-0.005		μΑ _{DC}
CLOCK IN	AND CLOCK R	• · · · · · · · · · · · · · · · · · · ·				
V _T +	CLK IN (Pin 4) Positive Going Threshold Voltage		2.7	3.1	3.5	V _{DC}
V _T -	CLK IN (Pin 4) Negative Going Threshold Voltage		1.5	1.8	2.1	V _{DC}
V _H	CLK IN (Pin 4) Hysteresis $(V_T+)-(V_T-)$		0.6	1.3	2.0	V _{DC}
V _{OUT} (0)	Logical "0" CLK R Output Voltage	I _O =360 μA V _{CC} =4.75 V _{DC}	!		0.4	V _{DC}
V _{OUT} (1)	Logical "1" CLK R Output Voltage	I _O = -360 μA V _{CC} = 4.75 V _{DC}	2.4	-		V _{DC}
DATA OUT	PUTS AND INTR					
V _{OUT} (0)	Logical "0" Output Voltage Data Outputs INTR Output	$I_{OUT} = 1.6 \text{ mA}, V_{CC} = 4.75 V_{DC}$ $I_{OUT} = 1.0 \text{ mA}, V_{CC} = 4.75 V_{DC}$			0.4 0.4	V _{DC} V _{DC}
V _{OUT} (1)	Logical "1" Output Voltage	$I_{O} = -360 \ \mu A$, $V_{CC} = 4.75 \ V_{DC}$	2.4			V _{DC}
V _{OUT} (1)	Logical "1" Output Voltage	$I_0 = -10 \ \mu A, V_{CC} = 4.75 \ V_{DC}$	4.5			V _{DC}
Ιουτ	TRI-STATE Disabled Output Leakage (All Data Buffers)	V _{OUT} =0 V _{DC} V _{OUT} =5 V _{DC}	-3		з	μΑ _{DC} μΑ _{DC}
SOURCE		V _{OUT} Short to Gnd, T _A = 25°C	4.5	6		mA _{DC}
ISINK		V_{OUT} Short to V_{CC} , $T_A = 25^{\circ}C$	9.0	16		mA _{DC}
POWER SU	IPPLY					
lcc	Supply Current (Includes Ladder Current)	$f_{CLK} = 640 \text{ kHz},$ $V_{REF}/2 = \text{NC}, T_A = 25^{\circ}\text{C}$ and $\overline{\text{CS}} = 5\text{V}$				
	ADC0801/02/03/04LCJ/05 ADC0804LCN/LCV/LCWM			1.1 1.9	1.8 2.5	mA mA

Note 2: All voltages are measured with respect to Gnd, unless otherwise specified. The separate A Gnd point should always be wired to the D Gnd.

Note 3: A zener diode exists, internally, from V_{CC} to Gnd and has a typical breakdown voltage of 7 V_{DC}.

Note 4: For $V_{IN}(-) \ge V_{IN}(+)$ the digital output code will be 0000 0000. Two on-chip diodes are tied to each analog input (see block diagram) which will forward conduct for analog input voltages one diode drop below ground or one diode drop greater than the V_{CC} supply. Be careful, during testing at low V_{CC} levels (4.5V), as high level analog input (5V) can cause this input diode to conduct-especially at elevated temperatures, and cause errors for analog inputs near full-scale. The spec allows 50 mV forward bias of either diode. This means that as long as the analog V_{IN} does not exceed the supply voltage by more than 50 mV, the output code will be correct. To achieve an absolute 0 V_{DC} to 5 V_{DC} input voltage range will therefore require a minimum supply voltage of 4.950 V_{DC} over temperature variations, initial tolerance and loading.

Note 5: Accuracy is guaranteed at f_{CLK} = 640 kHz. At higher clock frequencies accuracy can degrade. For lower clock frequencies, the duty cycle limits can be extended so long as the minimum clock high time interval or minimum clock low time interval is no less than 275 ns.

Note 6: With an asynchronous start pulse, up to 8 clock periods may be required before the internal clock phases are proper to start the conversion process. The start request is internally latched, see Figure 2 and section 2.0.

Note 7: The CS input is assumed to bracket the WR strobe input and therefore timing is dependent on the WR pulse width. An arbitrarily wide pulse width will hold the converter in a reset mode and the start of conversion is initiated by the low to high transition of the WR pulse (see timing diagrams).

Note 8: None of these A/Ds requires a zero adjust (see section 2.5.1). To obtain zero code at other analog input voltages see section 2.5 and Figure 5.

Note 9: The V_{REF}/2 pin is the center point of a two-resistor divider connected from V_{CC} to ground. In all versions of the ADC0801, ADC0802, ADC0803, and ADC0805, and in the ADC0804LCJ, each resistor is typically 16 kΩ. In all versions of the ADC0804 except the ADC0804LCJ, each resistor is typically 2.2 kΩ. Note 10: Human body model, 100 pF discharged through a 1.5 kΩ resistor.





3-20

6800 Interface







Absolute with a 2.500V Reference



Zero-Shift and Span Adjust: $2V\!\le\!V_{IN}\!\le\!5V$



Absolute with a 5V Reference







Directly Converting a Low-Level Signal A µP Interfaced Comparator VCC (5 VDC) VCC (S VDC) V m (+) Vc Vcr 10 µ I -A/D $0V \leq V_{jN} \leq 512 \text{ mV}$ A/D 1 M33 V_{IN}(-) VREF/ VREF/ VIN(-) 3.9k -15 VDC O For: $V_{IN}(+) > V_{IN}(-)$ 100 VOS ADJ Output = FF_{HEX} 10 ≶ 10 V_{REF}/2=256 mV For: V_{IN}(+)<V_{IN}(-) Output = 00_{HEX}

1 mV Resolution with μP Controlled Range



Digitizing a Current Flow



TL/H/5671-6











*Beckman Instruments #694-3-R10K resistor array

Low-Cost, µP Interfaced, Temperature-to-Digital Converter











Noise Filtering the Analog Input





Multiplexing Differential Inputs



unity-gain, 2nd order, low-pass filter Adding a separate filter for each channel increases system response time if an analog multiplexer is used





Increasing Bus Drive and/or Reducing Time on Bus





Sampling an AC Input Signal



Note 1: Oversample whenever possible [keep fs >2f(-60)] to eliminate input frequency folding (aliasing) and to allow for the skirt response of the filter.

Note 2: Consider the amplitude errors which are introduced within the passband of the filter.

70% Power Savings by Clock Gating



Power Savings by A/D and V_{REF} Shutdown



TL/H/5671-11

Functional Description

1.0 UNDERSTANDING A/D ERROR SPECS

A perfect A/D transfer characteristic (staircase waveform) is shown in *Figure 1a*. The horizontal scale is analog input voltage and the particular points labeled are in steps of 1 LSB (19.53 mV with 2.5V tied to the $V_{\text{REF}}/2$ pin). The digital output codes that correspond to these inputs are shown as D-1, D, and D+1. For the perfect A/D, not only will centervalue (A-1, A, A+1, . . .) analog inputs produce the correct output ditigal codes, but also each riser (the transitions between adjacent output codes) will be located $\pm \frac{1}{2}$ LSB away from each center-value. As shown, the risers are ideal and have no width. Correct digital output codes will be provided for a range of analog input voltages that extend $\pm \frac{1}{2}$ LSB from the ideal center-values. Each tread (the range of analog input voltage that provides the same digital output code) is therefore 1 LSB wide.

Figure 1b shows a worst case error plot for the ADC0801. All center-valued inputs are guaranteed to produce the correct output codes and the adjacent risers are guaranteed to be no closer to the center-value points than $\pm \frac{1}{4}$ LSB. In other words, if we apply an analog input equal to the centervalue $\pm \frac{1}{4}$ LSB, we guarantee that the A/D will produce the correct digital code. The maximum range of the position of the code transition is indicated by the horizontal arrow and it is guaranteed to be no more than $\frac{1}{2}$ LSB.

The error curve of *Figure 1c* shows a worst case error plot for the ADC0802. Here we guarantee that if we apply an analog input equal to the LSB analog voltage center-value the A/D will produce the correct digital code.

Next to each transfer function is shown the corresponding error plot. Many people may be more familiar with error plots than transfer functions. The analog input voltage to the A/D is provided by either a linear ramp or by the discrete output steps of a high resolution DAC. Notice that the error is continuously displayed and includes the quantization uncertainty of the A/D. For example the error at point 1 of *Figure 1a* is $+\frac{1}{2}$ LSB because the digital code appeared $\frac{1}{2}$ LSB in advance of the center-value of the tread. The error plots always have a constant negative slope and the abrupt upside steps are always 1 LSB in magnitude.



2.0 FUNCTIONAL DESCRIPTION

The ADC0801 series contains a circuit equivalent of the 256R network. Analog switches are sequenced by successive approximation logic to match the analog difference input voltage $[V_{IN}(+) - V_{IN}(-)]$ to a corresponding tap on the R network. The most significant bit is tested first and after 8 comparisons (64 clock cycles) a digital 8-bit binary code (1111 1111 = full-scale) is transferred to an output latch and then an interrupt is asserted (INTR makes a high-to-low transition). A conversion in process can be interrupted by issuing a second start command. The device may be operated in the free-running mode by connecting INTR to the WR input with $\overline{CS} = 0$. To ensure start-up under all possible conditions, an external WR pulse is required during the first power-up cycle.

On the high-to-low transition of the \overline{WR} input the internal SAR latches and the shift register stages are reset. As long as the \overline{CS} input and \overline{WR} input remain low, the A/D will remain in a reset state. Conversion will start from 1 to 8 clock periods after at least one of these inputs makes a low-to-high transition.

A functional diagram of the A/D converter is shown in *Figure 2*. All of the package pinouts are shown and the major logic control paths are drawn in heavier weight lines.

The converter is started by having CS and WR simultaneously low. This sets the start flip-flop (F/F) and the resulting "1" level resets the 8-bit shift register, resets the interrupt (INTR) F/F and inputs a "1" to the D flop, F/F1, which is at the input end of the 8-bit shift register. Internal clock signals then transfer this "1" to the Q output of F/F1. The AND gate, G1, combines this "1" output with a clock signal to provide a reset signal to the start F/F. If the set signal is no longer present (either WR or CS is a "1") the start F/F is reset and the 8-bit shift register then can have the "1" clocked in, which starts the conversion process. If the set signal were to still be present, this reset pulse would have no effect (both outputs of the start F/F would momentarily be at a "1" level) and the 8-bit shift register would continue to be held in the reset mode. This logic therefore allows for wide CS and WR signals and the converter will start after at least one of these signals returns high and the internal clocks again provide a reset signal for the start F/F.



Note 1: CS shown twice for clarity.



After the "1" is clocked through the 8-bit shift register (which completes the SAR search) it appears as the input to the D-type latch, LATCH 1. As soon as this "1" is output from the shift register, the AND gate, G2, causes the new digital word to transfer to the TRI-STATE output latches. When LATCH 1 is subsequently enabled, the Q output makes a high-to-low transition which causes the INTR F/F to set. An inverting buffer then supplies the INTR input signal.

Note that this $\overline{\text{SET}}$ control of the INTR F/F remains low for 8 of the external clock periods (as the internal clocks run at $\frac{1}{6}$ of the frequency of the external clock). If the data output is continuously enabled ($\overline{\text{CS}}$ and $\overline{\text{RD}}$ both held low), the INTR output will still signal the end of conversion (by a highto-low transition), because the $\overline{\text{SET}}$ input can control the Q output of the INTR F/F even though the RESET input is constantly at a "1" level in this operating mode. This $\overline{\text{INTR}}$ output will therefore stay low for the duration of the $\overline{\text{SET}}$ signal, which is 8 periods of the external clock frequency (assuming the A/D is not started during this interval).

When operating in the free-running or continuous conversion mode (INTR pin tied to WR and CS wired low—see also section 2.8), the START F/F is SET by the high-to-low transition of the INTR signal. This resets the SHIFT REGISTER which causes the input to the D-type latch, LATCH 1, to go low. As the latch enable input is still present, the \overline{Q} output will go high, which then allows the INTR F/F to be RESET. This reduces the width of the resulting INTR output pulse to only a few propagation delays (approximately 300 ns).

When data is to be read, the combination of both $\overline{\text{CS}}$ and $\overline{\text{RD}}$ being low will cause the INTR F/F to be reset and the TRI-STATE output latches will be enabled to provide the 8-bit digital outputs.

2.1 Digital Control Inputs

The digital control inputs (\overline{CS} , \overline{RD} , and \overline{WR}) meet standard T²L logic voltage levels. These signals have been renamed when compared to the standard A/D Start and Output Enable labels. In addition, these inputs are active low to allow an easy interface to microprocessor control busses. For non-microprocessor based applications, the \overline{CS} input (pin 1) can be grounded and the standard A/D Start function is obtained by an active low pulse applied at the \overline{WR} input (pin 3) and the Output Enable function is caused by an active low pulse at the \overline{RD} input (pin 2).

2.2 Analog Differential Voltage Inputs and Common-Mode Rejection

This A/D has additional applications flexibility due to the analog differential voltage input. The V_{IN}(-) input (pin 7) can be used to automatically subtract a fixed voltage value from the input reading (tare correction). This is also useful in 4 mA-20 mA current loop conversion. In addition, commonde noise can be reduced by use of the differential input. The time interval between sampling V_{IN}(+) and V_{IN}(-) is 4- $\frac{1}{2}$ clock periods. The maximum error voltage due to this

slight time difference between the input voltage samples is given by:

$$\Delta V_{e}(MAX) = (V_{P}) (2\pi f_{cm}) \left(\frac{4.5}{f_{CLK}}\right),$$

where:

 ΔV_e is the error voltage due to sampling delay

V_P is the peak value of the common-mode voltage

fcm is the common-mode frequency

As an example, to keep this error to 1/4 LSB (~5 mV) when operating with a 60 Hz common-mode frequency, f_{cm} , and using a 640 kHz A/D clock, f_{CLK} , would allow a peak value of the common-mode voltage, V_P, which is given by:

$$V_{P} = \frac{\left[\Delta V_{e(MAX)} \left(f_{CLK}\right)\right]}{\left(2\pi f_{cm}\right) \left(4.5\right)}$$

or

$$V_{\mathsf{P}} = \frac{(5 \times 10^{-3}) \ (640 \times 10^{3})}{(6.28) \ (60) \ (4.5)}$$

which gives

V_P ≅ 1.9V.

The allowed range of analog input voltages usually places more severe restrictions on input common-mode noise levels.

An analog input voltage with a reduced span and a relatively large zero offset can be handled easily by making use of the differential input (see section 2.4 Reference Voltage).

2.3 Analog Inputs

2.3.1 Input Current

Normal Mode

Due to the internal switching action, displacement currents will flow at the analog inputs. This is due to on-chip stray capacitance to ground as shown in *Figure 3*.



FIGURE 3. Analog Input Impedance

The voltage on this capacitance is switched and will result in currents entering the V_{IN}(+) input pin and leaving the V_{IN}(-) input which will depend on the analog differential input voltage levels. These current transients occur at the leading edge of the internal clocks. They rapidly decay and *do not cause errors* as the on-chip comparator is strobed at the end of the clock period.

Fault Mode

If the voltage source applied to the V_{IN}(+) or V_{IN}(-) pin exceeds the allowed operating range of V_{CC}+50 mV, large input currents can flow through a parasitic diode to the V_{CC} pin. If these currents can exceed the 1 mA max allowed spec, an external diode (1N914) should be added to bypass this current to the V_{CC} pin (with the current bypassed with this diode, the voltage at the V_{IN}(+) pin can exceed the V_{CC} voltage by the forward voltage of this diode).

2.3.2 Input Bypass Capacitors

Bypass capacitors at the inputs will average these charges and cause a DC current to flow through the output resistances of the analog signal sources. This charge pumping action is worse for continuous conversions with the VIN(+) input voltage at full-scale. For continuous conversions with a 640 kHz clock frequency with the VIN(+) input at 5V, this DC current is at a maximum of approximately 5 µA. Therefore, bypass capacitors should not be used at the analog inputs or the V_{RFF}/2 pin for high resistance sources (> 1 $k\Omega$). If input bypass capacitors are necessary for noise filtering and high source resistance is desirable to minimize capacitor size, the detrimental effects of the voltage drop across this input resistance, which is due to the average value of the input current, can be eliminated with a full-scale adjustment while the given source resistor and input bypass capacitor are both in place. This is possible because the average value of the input current is a precise linear function of the differential input voltage.

2.3.3 Input Source Resistance

Large values of source resistance where an input bypass capacitor is not used, *will not cause errors* as the input currents settle out prior to the comparison time. If a low pass filter is required in the system, use a low valued series resistor ($\leq 1 \ k\Omega$) for a passive RC section or add an op amp RC active low pass filter. For low source resistance applications, ($\leq 1 \ k\Omega$), a 0.1 μF bypass capacitor at the inputs will prevent noise pickup due to series lead inductance of a long wire. A 100\Omega series resistor can be used to isolate this capacitor—both the R and C are placed outside the feedback loop—from the output of an op amp, if used.

2.3.4 Noise

The leads to the analog inputs (pin 6 and 7) should be kept as short as possible to minimize input noise coupling. Both noise and undesired digital clock coupling to these inputs can cause system errors. The source resistance for these inputs should, in general, be kept below 5 kΩ. Larger values of source resistance can cause undesired system noise pickup. Input bypass capacitors, placed from the analog inputs to ground, will eliminate system noise pickup but can create analog scale errors as these capacitors will average the transient input switching currents of the A/D (see section 2.3.1). This scale error depends on both a large source resistance and the use of an input bypass capacitor. This error can be eliminated by doing a full-scale adjustment of the A/D (adjust $V_{REF}/2$ for a proper full-scale reading—see section 2.5.2 on Full-Scale Adjustment) with the source resistance and input bypass capacitor in place.

2.4 Reference Voltage

2.4.1 Span Adjust

For maximum applications flexibility, these A/Ds have been designed to accommodate a 5 V_{DC} , 2.5 V_{DC} or an adjusted voltage reference. This has been achieved in the design of the IC as shown in *Figure 4*.



TL/H/5671-15

FIGURE 4. The V_{REFERENCE} Design on the IC Notice that the reference voltage for the IC is either 1/2 of the voltage applied to the V_{CC} supply pin, or is equal to the voltage that is externally forced at the V_{REF}/2 pin. This allows for a ratiometric voltage reference using the V_{CC} supply, a 5 V_{DC} reference voltage can be used for the V_{CC} supply or a voltage less than 2.5 V_{DC} can be applied to the V_{REF}/2 input for increased application flexibility. The internal gain to the V_{REF}/2 input is 2, making the full-scale differential input voltage twice the voltage at pin 9.

An example of the use of an adjusted reference voltage is to accommodate a reduced span—or dynamic voltage range of the analog input voltage. If the analog input voltage were to range from 0.5 V_{DC} to 3.5 V_{DC}, instead of 0V to 5 V_{DC} applied to the V_{IN}(-) pin to absorb the offset, the reference voltage can be made equal to $\frac{1}{2}$ of the 3V span or 1.5 V_{DC}. The A/D now will encode the V_{IN}(+) signal from 0.5V to 3.5 V_{DC} input corresponding to zero and the 3.5 V_{DC} input corresponding to full-scale. The full 8 bits of resolution are therefore applied over this reduced analog input voltage range.



FIGURE 5. Adapting the A/D Analog Input Voltages to Match an Arbitrary Input Signal Range

2.4.2 Reference Accuracy Requirements

The converter can be operated in a ratiometric mode or an absolute mode. In ratiometric converter applications, the magnitude of the reference voltage is a factor in both the output of the source transducer and the output of the A/D converter and therefore cancels out in the final digital output code. The ADC0805 is specified particularly for use in ratiometric applications with no adjustments required. In absolute conversion applications, both the initial value and the temperature stability of the reference voltage are important factors in the accuracy of the A/D converter. For VBFF/2 voltages of 2.4 V_{DC} nominal value, initial errors of ±10 mV_{DC} will cause conversion errors of ± 1 LSB due to the gain of 2 of the V_{REF}/2 input. In reduced span applications, the initial value and the stability of the VBFF/2 input voltage become even more important. For example, if the span is reduced to 2.5V, the analog input LSB voltage value is correspondingly reduced from 20 mV (5V span) to 10 mV and 1 LSB at the V_{REF}/2 input becomes 5 mV. As can be seen, this reduces the allowed initial tolerance of the reference voltage and requires correspondingly less absolute change with temperature variations. Note that spans smaller than 2.5V place even tighter requirements on the initial accuracy and stability of the reference source.

In general, the magnitude of the reference voltage will require an initial adjustment. Errors due to an improper value of reference voltage appear as full-scale errors in the A/D transfer function. IC voltage regulators may be used for references if the ambient temperature changes are not excessive. The LM336B 2.5V IC reference diode (from National Semiconductor) has a temperature stability of 1.8 mV typ (6 mV max) over $0^{\circ}C \le T_{A} \le +70^{\circ}C$. Other temperature range parts are also available.

2.5 Errors and Reference Voltage Adjustments

2.5.1 Zero Error

The zero of the A/D does not require adjustment. If the minimum analog input voltage value, V_{IN(MIN)}, is not ground, a zero offset can be done. The converter can be made to output 0000 0000 digital code for this minimum input voltage by biasing the A/D V_{IN}(-) input at this V_{IN(MIN)} value (see Applications section). This utilizes the differential mode operation of the A/D.

The zero error of the A/D converter relates to the location of the first riser of the transfer function and can be measured by grounding the V_{IN} (-) input and applying a small magnitude positive voltage to the V_{IN} (+) input. Zero error is the difference between the actual DC input voltage that is necessary to just cause an output digital code transition from 0000 0000 to 0000 0001 and the ideal $^{1}\!/_{2}$ LSB value ($^{1}\!/_{2}$ LSB = 9.8 mV for V_{REF}/2=2.500 V_{DC}).

2.5.2 Full-Scale

The full-scale adjustment can be made by applying a differential input voltage that is $1\frac{1}{2}$ LSB less than the desired analog full-scale voltage range and then adjusting the magnitude of the V_{REF}/2 input (pin 9 or the V_{CC} supply if pin 9 is not used) for a digital output code that is just changing from 1111 1110 to 1111 1111.

2.5.3 Adjusting for an Arbitrary Analog Input Voltage Range

If the analog zero voltage of the A/D is shifted away from ground (for example, to accommodate an analog input signal that does not go to ground) this new zero reference should be properly adjusted first. A V_{IN}(+) voltage that equals this desired zero reference plus $\frac{1}{2}$ LSB (where the LSB is calculated for the desired analog span, 1 LSB = analog span/256) is applied to pin 6 and the zero reference voltage at pin 7 should then be adjusted to just obtain the 00_{HEX} to 01_{HEX} code transition.

The full-scale adjustment should then be made (with the proper $V_{IN}(-)$ voltage applied) by forcing a voltage to the $V_{IN}(+)$ input which is given by:

$$V_{\text{IN}}(+) \text{ fs adj} = V_{\text{MAX}} - 1.5 \left[\frac{(V_{\text{MAX}} - V_{\text{MIN}})}{256} \right]$$

where:

 V_{MAX} = The high end of the analog input range and

 $V_{\mbox{MIN}}\mbox{=}$ the low end (the offset zero) of the analog range. (Both are ground referenced.)

The V_{REF}/2 (or V_{CC}) voltage is then adjusted to provide a code change from FE_{HEX} to FF_{HEX}. This completes the adjustment procedure.

2.6 Clocking Option

The clock for the A/D can be derived from the CPU clock or an external RC can be added to provide self-clocking. The CLK IN (pin 4) makes use of a Schmitt trigger as shown in *Figure 6.*



FIGURE 6. Self-Clocking the A/D

Heavy capacitive or DC loading of the clock R pin should be avoided as this will disturb normal converter operation. Loads less than 50 pF, such as driving up to 7 A/D converter clock inputs from a single clock R pin of 1 converter, are allowed. For larger clock line loading, a CMOS or low power TTL buffer or PNP input logic should be used to minimize the loading on the clock R pin (do not use a standard TTL buffer).

2.7 Restart During a Conversion

If the A/D is restarted (\overline{CS} and \overline{WR} go low and return high) during a conversion, the converter is reset and a new conversion is started. The output data latch is not updated if the conversion in process is not allowed to be completed, therefore the data of the previous conversion remains in this latch. The INTR output simply remains at the "1" level.

2.8 Continuous Conversions

For operation in the free-running mode an initializing pulse should be used, following power-up, to ensure circuit operation. In this application, the \overline{CS} input is grounded and the \overline{WR} input is tied to the \overline{INTR} output. This \overline{WR} and \overline{INTR} node should be momentarily forced to logic low following a power-up cycle to guarantee operation.

2.9 Driving the Data Bus

This MOS A/D, like MOS microprocessors and memories, will require a bus driver when the total capacitance of the data bus gets large. Other circuitry, which is tied to the data bus, will add to the total capacitive loading, even in TRI-STATE (high impedance mode). Backplane bussing also greatly adds to the stray capacitance of the data bus.

There are some alternatives available to the designer to handle this problem. Basically, the capacitive loading of the data bus slows down the response time, even though DC specifications are still met. For systems operating with a relatively slow CPU clock frequency, more time is available in which to establish proper logic levels on the bus and therefore higher capacitive loads can be driven (see typical characteristics curves).

At higher CPU clock frequencies time can be extended for I/O reads (and/or writes) by inserting wait states (8080) or using clock extending circuits (6800).

Finally, if time is short and capacitive loading is high, external bus drivers must be used. These can be TRI-STATE buffers (low power Schottky such as the DM74LS240 series is recommended) or special higher drive current products which are designed as bus drivers. High current bipolar bus drivers with PNP inputs are recommended.

2.10 Power Supplies

Noise spikes on the V_{CC} supply line can cause conversion errors as the comparator will respond to this noise. A low inductance tantalum filter capacitor should be used close to the converter V_{CC} pin and values of 1 μ F or greater are recommended. If an unregulated voltage is available in the system, a separate LM340LAZ-5.0, TO-92, 5V voltage regulator for the converter (and other analog circuitry) will greatly reduce digital noise on the V_{CC} supply.

2.11 Wiring and Hook-Up Precautions

Standard digital wire wrap sockets are not satisfactory for breadboarding this A/D converter. Sockets on PC boards can be used and all logic signal wires and leads should be grouped and kept as far away as possible from the analog signal leads. Exposed leads to the analog inputs can cause undesired digital noise and hum pickup, therefore shielded leads may be necessary in many applications.

A single point analog ground that is separate from the logic ground points should be used. The power supply bypass capacitor and the self-clocking capacitor (if used) should both be returned to digital ground. Any V_{REF}/2 bypass capacitors, analog input filter capacitors, or input signal shielding should be returned to the analog ground point. A test for proper grounding is to measure the zero error of the A/D converter. Zero errors in excess of 1/4 LSB can usually be traced to improper board layout and wiring (see section 2.5.1 for measuring the zero error).

3.0 TESTING THE A/D CONVERTER

There are many degrees of complexity associated with testing an A/D converter. One of the simplest tests is to apply a known analog input voltage to the converter and use LEDs to display the resulting digital output code as shown in *Figure 7*.

For ease of testing, the V_{REF}/2 (pin 9) should be supplied with 2.560 V_{DC} and a V_{CC} supply voltage of 5.12 V_{DC} should be used. This provides an LSB value of 20 mV.

If a full-scale adjustment is to be made, an analog input voltage of 5.090 V_{DC} (5.120–1½ LSB) should be applied to the V_{IN}(+) pin with the V_{IN}(-) pin grounded. The value of the V_{REF}/2 input voltage should then be adjusted until the digital output code is just changing from 1111 1110 to 1111 1111. This value of V_{REF}/2 should then be used for all the tests.

The digital output LED display can be decoded by dividing the 8 bits into 2 hex characters, the 4 most significant (MS) and the 4 least significant (LS). Table I shows the fractional binary equivalent of these two 4-bit groups. By adding the voltages obtained from the "VMS" and "VLS" columns in Table I, the nominal value of the digital display (when



 $V_{REF}/2=2.560V)$ can be determined. For example, for an output LED display of 1011 0110 or B6 (in hex), the voltage values from the table are 3.520 + 0.120 or 3.640 V_{DC} . These voltage values represent the center-values of a perfect A/D converter. The effects of quantization error have to be accounted for in the interpretation of the test results.

For a higher speed test system, or to obtain plotted data, a digital-to-analog converter is needed for the test set-up. An accurate 10-bit DAC can serve as the precision voltage source for the A/D. Errors of the A/D under test can be expressed as either analog voltages or differences in 2 digital words.

A basic A/D tester that uses a DAC and provides the error as an analog output voltage is shown in *Figure 8*. The 2 op amps can be eliminated if a lab DVM with a numerical subtraction feature is available to read the difference voltage, "A-C", directly. The analog input voltage can be supplied by a low frequency ramp generator and an X-Y plotter can be used to provide analog error (Y axis) versus analog input (X axis).

For operation with a microprocessor or a computer-based test system, it is more convenient to present the errors digitally. This can be done with the circuit of *Figure 9*, where the output code transitions can be detected as the 10-bit DAC is incremented. This provides $\frac{1}{4}$ LSB steps for the 8-bit A/D under test. If the results of this test are automatically plotted with the analog input on the X axis and the error (in LSB's) as the Y axis, a useful transfer function of the A/D under test results. For acceptance testing, the plot is not necessary and the testing speed can be increased by establishing internal limits on the allowed error for each code.

4.0 MICROPROCESSOR INTERFACING

To dicuss the interface with 8080A and 6800 microprocessors, a common sample subroutine structure is used. The microprocessor starts the A/D, reads and stores the results of 16 successive conversions, then returns to the user's program. The 16 data bytes are stored in 16 successive memory locations. All Data and Addresses will be given in hexadecimal form. Software and hardware details are provided separately for each type of microprocessor.

4.1 Interfacing 8080 Microprocessor Derivatives (8048, 8085)

This converter has been designed to directly interface with derivatives of the 8080 microprocessor. The A/D can be mapped into memory space (using standard memory address decoding for CS and the MEMR and MEMW strobes) or it can be controlled as an I/O device by using the I/O R and $\overline{I/OW}$ strobes and decoding the address bits A0 \rightarrow A7 (or address bits A8 \rightarrow A15 as they will contain the same 8-bit address information) to obtain the CS input. Using the I/O space provides 256 additional addresses and may allow a simpler 8-bit address decoder but the data can only be input to the accumulator. To make use of the additional memory reference instructions, the A/D should be mapped into memory space. An example of an A/D in I/O space is shown in *Figure 10*.

				Jes	cript	ion (0	Continu	ued)					
					ANALOG I VOL			"R	R R R H H H H H H H H H H H H H		WANALOG 		
					DI	GITAL 💯		DAC100 10-BIT DAC				NL T	
							FIC	GURE 9. E	Basic "Digital" A/D) Tester		TL/H/567	1–19
НЕХ		BIN	ARY			TA	BLE 1.	DECODI	Basic "Digital" A/D NG THE DIGITAL O BINARY VALUE FC	Ουτρυτ		OUTPUT	VOLTAGE VALUES
HEX		BIN	ARY				BLE I. FRAC	DECODI	NG THE DIGITAL O BINARY VALUE FC	OUTPUT		OUTPUT CENTER WI V _{REF} /2=	VOLTAGE VALUES ITH 2.560 VDC
							BLE 1.	DECODI	NG THE DIGITAL O	OUTPUT	LEDs	OUTPUT CENTER Wi V _{REF} /2= VMS GROUP*	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP*
F	1	1	1	1 0			BLE I. FRAC	DECODI	NG THE DIGITAL O BINARY VALUE FC	OUTPUT OR ROUP		OUTPUT CENTER Wi V _{REF} /2= VMS GROUP* 4.800	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP* 0.300
				1 0 1			BLE I. FRAC	DECODI	NG THE DIGITAL O BINARY VALUE FC	OUTPUT	LEDs	OUTPUT CENTER Wi V _{REF} /2= VMS GROUP*	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP*
F E	1	1	1	0			BLE I. FRAC	DECODI CTIONAL	NG THE DIGITAL O BINARY VALUE FC	OUTPUT OR ROUP	LEDs 15/256	OUTPUT CENTER Wi V _{REF} /2= VMS GROUP* 4.800 4.480	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP* 0.300 0.280
F E D	1 1 1	1 1 1 1 0	1 1 0	0 1		MS G	BLE I. FRAC	DECODI CTIONAL	NG THE DIGITAL O BINARY VALUE FC LS GF 3/64	OUTPUT OR ROUP 7/128	LEDs 15/256	OUTPUT CENTER WI VREF/2 = VMS GROUP* 4.800 4.480 4.160	VOLTAGE VALUES TH 2.560 V _{DC} VLS GROUP* 0.300 0.280 0.260 0.240 0.220
F E D C B A	1 1 1 1 1	1 1 1 1 0 0	1 1 0 1 1	0 1 0 1 0		MS G	BLE I. FRAC	DECODI CTIONAL 15/16 13/16 11/16	NG THE DIGITAL O BINARY VALUE FC LS GF 3/64	OUTPUT OR ROUP	LEDs 15/256 13/256 11/256	OUTPUT CENTER Wi VREF/2= VMS GROUP* 4.800 4.480 4.160 3.840 3.520 3.200	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP* 0.300 0.280 0.260 0.240 0.220 0.200
F E D C B A 9	1 1 1 1 1 1	1 1 1 1 0 0 0	1 1 0 1 1 1	0 1 0 1 0 1	1/0	MS G	FRAC	DECODI CTIONAL 15/16 13/16	NG THE DIGITAL O BINARY VALUE FC LS GF 3/64	OUTPUT OR ROUP 7/128	LEDs 15/256 13/256	OUTPUT CENTER WI VREF/2= VMS GROUP* 4.800 4.480 4.160 3.840 3.520 3.200 2/880	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP* 0.300 0.280 0.260 0.240 0.220 0.200 0.180
F E D C B A 9 8	1 1 1 1 1 1 1	1 1 1 0 0 0 0	1 1 0 1 1 0 0	0 1 0 1 0 1 0	1/2	MS G	FRAC	DECODI CTIONAL 15/16 13/16 11/16 9/16	NG THE DIGITAL O BINARY VALUE FC LS GF 3/64	OUTPUT OR ROUP 7/128	LEDs 15/256 13/256 11/256 9/256	OUTPUT CENTER WI VREF/2= VMS GROUP* 4.800 4.480 4.160 3.840 3.520 3.200 2/880 2/560	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP* 0.300 0.280 0.260 0.240 0.220 0.200 0.180 0.160
F E D C B A 9 8 7	1 1 1 1 1 1 1 1 0	1 1 1 0 0 0 0 1	1 1 0 1 1 0 0	0 1 0 1 0 1 0 1	1/2	MS G	BLE I. FRAC ROUP 7/8 5/8	DECODI CTIONAL 15/16 13/16 11/16	NG THE DIGITAL O BINARY VALUE FC LS GF 3/64	DUTPUT OR 7/128 5/128	LEDs 15/256 13/256 11/256	OUTPUT CENTER Wi VREF/2 = VMS GROUP* 4.800 4.480 4.160 3.840 3.520 3.200 2/880 2/560 2.240	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP* 0.300 0.280 0.260 0.240 0.220 0.200 0.180 0.160 0.140
F E D C B A 9 8	1 1 1 1 1 1 1	1 1 1 0 0 0 0	1 1 0 1 1 0 0	0 1 0 1 0 1 0	1/2	MS G	FRAC	DECODI CTIONAL 15/16 13/16 11/16 9/16	NG THE DIGITAL O BINARY VALUE FC LS GF 3/64	OUTPUT OR ROUP 7/128	LEDs 15/256 13/256 11/256 9/256	OUTPUT CENTER WI VREF/2= VMS GROUP* 4.800 4.480 4.160 3.840 3.520 3.200 2/880 2/560	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP* 0.300 0.280 0.260 0.240 0.220 0.200 0.180 0.160
F E D C B A 9 8 7 6	1 1 1 1 1 1 1 1 0 0	1 1 1 0 0 0 0 1 1	1 1 0 1 1 0 0 1 1 1	0 1 0 1 0 1 0 1 0	1/2	MS G	BLE I. FRAC ROUP 7/8 5/8	DECODI CTIONAL 15/16 13/16 11/16 9/16 7/16	NG THE DIGITAL O BINARY VALUE FC LS GF 3/64	DUTPUT OR 7/128 5/128	LEDs 15/256 13/256 11/256 9/256 7/256	OUTPUT CENTER Wi VREF/2= VMS GROUP* 4.800 4.480 4.160 3.840 3.520 3.200 2/880 2/560 2.240 1.920	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP* 0.300 0.280 0.260 0.240 0.220 0.200 0.180 0.160 0.140 0.120
F E D C B A 9 8 7 6 5	1 1 1 1 1 1 1 0 0 0	1 1 1 0 0 0 0 0 1 1 1	1 1 0 1 1 1 0 0 1 1 1 0	0 1 0 1 0 1 0 1 0 1 0	1/2	MS G 3/4	BLE I. FRAC ROUP 7/8 5/8	DECODI CTIONAL 15/16 13/16 11/16 9/16 7/16	NG THE DIGITAL O BINARY VALUE FC LS GF 3/64	DUTPUT OR 7/128 5/128	LEDs 15/256 13/256 11/256 9/256 7/256	OUTPUT CENTER WI VREF/2= VMS GROUP* 4.800 4.480 4.160 3.840 3.520 3.200 2/880 2/560 2.240 1.920 1.600	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP* 0.300 0.280 0.260 0.240 0.220 0.200 0.180 0.160 0.140 0.120 0.100
F E D C B A 9 8 7 6 5 4	1 1 1 1 1 1 1 0 0 0 0	1 1 1 0 0 0 0 0 1 1 1 1 1	1 1 0 1 1 1 0 0 1 1 1 0 0	0 1 0 1 0 1 0 1 0 1 0	1/2	MS G 3/4	BLE I. FRAC ROUP 7/8 5/8	DECODI CTIONAL 15/16 13/16 11/16 9/16 7/16 5/16	NG THE DIGITAL O BINARY VALUE FC LS GF 3/64 1/32	DUTPUT OR 7/128 5/128	LEDs 15/256 13/256 11/256 9/256 7/256 2/256	OUTPUT CENTER WI VREF/2= VMS GROUP* 4.800 4.480 4.160 3.840 3.520 3.200 2/880 2/560 2.240 1.920 1.600 1./280	VOLTAGE VALUES ITH 2.560 V _{DC} VLS GROUP* 0.300 0.280 0.260 0.240 0.220 0.200 0.180 0.160 0.140 0.120 0.100 0.080

Functio	onal Desc	ription (Continued)		
			<u>></u>	INT (14)
			10k	
			U,	V _{CC} 20 O5V+
				DB0 17 DB0 (13)*
		5 CLK IN		DB1 16 DB1 (16)*
	ANALOG		A/U	DB2 (11)* DB3 (9)*
	INPUTS	30		DB4 (5)*
		150 pFA GND	r	DB5 13 DB5 (18)*
			r	DB6 12 DB6 (20)*
			r	DB7 (7)*
			ר [™]	
			- 	
			OUT VCC	
		6 T5		B5 AD15 (36)
		T4 T3	DM8131	AD14 (39)
		T2	BUS COMPARATOR	AD13 (38) B2 AD12 (37)
			COMPARATOR	AD11 (40)
		ф то		B0 AD10 (1)
			1 1	
			ه	
			m	TL/H/5671–20
		e 1: *Pin numbers for the DP8228	-	
				h a 1 kΩ resistor to generate the RST 7 y the accompanying sample program.
			DC0801-INS8080	
		FIGURE IO. A	JC0801-11136080	
				1-INS8080A CPU INTERFACE
0038	C3 00 03	RST 7:	JMP LD DA	ATA
•	•	•		
•	•	•		
0100	21 00 02	START:	LXI H 0200H	;HL pair will point to
				; data storage locations
0103	31 00 04	RETURN:	LXI SP 0400H	; Initialize stack pointer (Note 1)
0106	7D		MOVA, L	; Test # of bytes entered
0107	FE OF		CPI OF H	; If # = 16. JMP to
0109	CA 13 01		JZ CONT	; user program
0100	D3 E0		OUT EO H	; Start A/D
010E	FB	T.00D.	EI	; Enable interrupt
010F	00 07 0 F 0 I	L00P:	NOP	; Loop until end of
0110 0113	C3 OF 01	CONT:	JMP LOOP	; conversion
0113	•	•	•	
-	•	(User program to	•	
•	•	process data)	•	
•	•	•	•	
•	•	•	•	
0300	DBEO	LD DATA:	IN EO H	; Load data into accumulator
0302	77		MOV M, A	; Store data
0303	23		INX H	; Increment storage pointer
0304	C3 03 01		JMP RETURN	,

Note 1: The stack pointer must be dimensioned because a RST 7 instruction pushes the PC onto the stack.

Note 2: All address used were arbitrarily chosen.

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The standard control bus signals of the 8080 \overline{CS} , \overline{RD} and \overline{WR}) can be directly wired to the digital control inputs of the A/D and the bus timing requirements are met to allow both starting the converter and outputting the data onto the data bus. A bus driver should be used for larger microprocessor systems where the data bus leaves the PC board and/or must drive capacitive loads larger than 100 pF.

4.1.1 Sample 8080A CPU Interfacing Circuitry and Program

The following sample program and associated hardware shown in *Figure 10* may be used to input data from the converter to the INS8080A CPU chip set (comprised of the INS8080A microprocessor, the INS8228 system controller and the INS8224 clock generator). For simplicity, the A/D is controlled as an I/O device, specifically an 8-bit bi-directional port located at an arbitrarily chosen port address, E0. The TRI-STATE output capability of the A/D eliminates the need for a peripheral interface device, however address decoding is still required to generate the appropriate \overline{CS} for the converter.

It is important to note that in systems where the A/D converter is 1-of-8 or less I/O mapped devices, no address decoding circuitry is necessary. Each of the 8 address bits (A0 to A7) can be directly used as \overline{CS} inputs—one for each I/O device.

4.1.2 INS8048 Interface

The INS8048 interface technique with the ADC0801 series (see *Figure 11*) is simpler than the 8080A CPU interface. There are 24 I/O lines and three test input lines in the 8048. With these extra I/O lines available, one of the I/O lines (bit 0 of port 1) is used as the chip select signal to the A/D, thus eliminating the use of an external address decoder. Bus control signals RD, WR and INT of the 8048 are tied directly to the A/D. The 16 converted data words are stored at onchip RAM locations from 20 to 2F (Hex). The RD and WR signals are generated by reading from and writing into a dummy address, respectively. A sample interface program is shown below.



4.2 Interfacing the Z-80

The Z-80 control bus is slightly different from that of the 8080. General RD and WR strobes are provided and separate memory request, MREQ, and I/O request, IORQ, signals are used which have to be combined with the generalized strobes to provide the equivalent 8080 signals. An advantage of operating the A/D in I/O space with the Z-80 is that the CPU will automatically insert one wait state (the RD and WR strobes are extended one clock period) to allow more time for the I/O devices to respond. Logic to map the A/D in I/O space is shown in *Figure 13*.



FIGURE 13. Mapping the A/D as an I/O Device for Use with the Z-80 CPU

Additional I/O advantages exist as software DMA routines are available and use can be made of the output data transfer which exists on the upper 8 address lines (A8 to A15) during I/O input instructions. For example, MUX channel selection for the A/D can be accomplished with this operating mode.

4.3 Interfacing 6800 Microprocessor Derivatives (6502, etc.)

The control bus for the 6800 microprocessor derivatives does not use the \overline{RD} and \overline{WR} strobe signals. Instead it employs a single R/\overline{W} line and additional timing, if needed, can be derived fom the $\phi 2$ clock. All I/O devices are memory mapped in the 6800 system, and a special signal, VMA, indicates that the current address is valid. *Figure 14* shows an interface schematic where the A/D is memory mapped in the 6800 system. For simplicity, the \overline{CS} decoding is shown using $\frac{1}{2}$ DM8092. Note that in many 6800 systems, an al-

ready decoded $\overline{4/5}$ line is brought out to the common bus at pin 21. This can be tied directly to the \overline{CS} pin of the A/D, provided that no other devices are addressed at HX ADDR: 4XXX or 5XXX.

The following subroutine performs essentially the same function as in the case of the 8080A interface and it can be called from anywhere in the user's program.

In *Figure 15* the ADC0801 series is interfaced to the M6800 microprocessor through (the arbitrarily chosen) Port B of the MC6820 or MC6821 Peripheral Interface Adapter, (PIA). Here the \overline{CS} pin of the A/D is grounded since the PIA is already memory mapped in the M6800 system and no \overline{CS} decoding is necessary. Also notice that the A/D output data lines are connected to the microprocessor bus under program control through the PIA and therefore the A/D \overline{RD} pin can be grounded.

A sample interface program equivalent to the previous one is shown below *Figure 15*. The PIA Data and Control Registers of Port B are located at HEX addresses 8006 and 8007, respectively.

5.0 GENERAL APPLICATIONS

The following applications show some interesting uses for the A/D. The fact that one particular microprocessor is used is not meant to be restrictive. Each of these application circuits would have its counterpart using any microprocessor that is desired.

5.1 Multiple ADC0801 Series to MC6800 CPU Interface

To transfer analog data from several channels to a single microprocessor system, a multiple converter scheme presents several advantages over the conventional multiplexer single-converter approach. With the ADC0801 series, the differential inputs allow individual span adjustment for each channel. Furthermore, all analog input channels are sensed simultaneously, which essentially divides the microprocessor's total system servicing time by the number of channels, since all conversions occur simultaneously. This scheme is shown in *Figure 16*.



	SAMPLE I	PROGRAM FOR /	FIGURE 14 AD	C0801-MC6800 C	PU INTERFACE
0010	DF 36	DATAIN	STX	TEMP2	; Save contents of X
0012	CE 00 2C		LDX	# \$ 002C	; Upon IRQ low CPU
0015	FF FF F8		STX	\$FFF8	; jumps to 002C
0018	B7 50 00		STAA	\$5000	; Start ADC0801
001B	OE		CLI		
001C	3E	CONVRT	WAI		;Wait for interrupt
001D	DE 34		LDX	TEMP1	
OOlF	8C 02 0F		CPX	# \$ 020F	; Is final data stored?
0022	27 14		BEQ	ENDP	
0024	B7 50 00		STAA	\$5000	; Restarts ADC0801
0027	08		INX		
0028	DF 34		STX	TEMPL	
002A	20 F0		BRA	CONVRT	
0020	DE 34	INTRPT	LDX	TEMPL	
002E	B6 50 00		LDAA	\$5000	; Read data
0031	A7 00		STAA	х	; Store it at X
0033	3B		RTI		
0034	02 00	TEMP1	FDB	\$0200	; Starting address for
					; data storage
0036	00 00	TEMP2	FDB	\$0000	
0038	CE 02 00	ENDP	LDX	#\$0200	; Reinitialize TEMP1
003B	DF 34		STX	TEMPL	
003D	DE 36		LDX	TEMP2	
003F	39		RTS		; Return from subroutine ; To user's program

Note 1: In order for the microprocessor to service subroutines and interrupts, the stack pointer must be dimensioned in the user's program.





TL/H/5671-25

SAMPLE PROGRAM FOR FIGURE 15 ADC0801-MC6820 PIA INT	ERFACE
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	SAMPLE	-nounam ron	FIGURE 15 K	DC0001-MC002	
0010	CE 00 38	DATAIN	LDX	#\$0038	; Upon IRQ low CPU
0013	FF FF F8		STX	\$FFF8	; jumps to 0038
0016	B6 80 06		LDAA	PIAORB	; Clear possible IRQ flags
0019	4F		CLRA		
001A	B7 80 07		STAA	PIACRB	
001D	B7 80 06		STAA	PIAORB	; Set Port Bas input
0020	OE		CLI		
0021	C6 34		LDAB	#\$34	
0023	86 3D		LDAA	#\$3D	
0025	F7 80 07	CONVRT	STAB	PIACRB	; Starts ADC0801
0028	B7 80 07		STAA	PIACRB	
002B	3E		WAI		;Wait for interrupt
0020	DE 40		LDX	TEMP1	
002E	8C 02 0F		CPX	#\$020F	; Is final data stored?
0031	27 OF		BEQ	ENDP	
0033	08		INX		
0034	DF 40		STX	TEMPL	
0036	20 ED		BRA	CONVRT	
0038	DE 40	INTRPT	LDX	TEMPL	
003A	B6 80 06		LDAA	PIAORB	; Read data in
003D	A7 00		STAA	x	; Store it at X
003F	3B		RTI		
0040	02 00	TEMP1	FDB	\$0200	; Starting address for
					; data storage
0042	CE 02 00	ENDP	LDX	#\$0200	;Reinitialize TEMP1
0045	DF 40		STX	TEMP1	
0047	39		RTS		; Return from subroutine
		PIAORB	EQU	\$8006	;To user's program
		PIACRB	EQU	\$8007	

The following schematic and sample subroutine (DATA IN) may be used to interface (up to) 8 ADC0801's directly to the MC6800 CPU. This scheme can easily be extended to allow the interface of more converters. In this configuration the converters are (arbitrarily) located at HEX address 5000 in the MC6800 memory space. To save components, the clock signal is derived from just one RC pair on the first converter. This output drives the other A/Ds.

All the converters are started simultaneously with a STORE instruction at HEX address 5000. Note that any other HEX address of the form 5XXX will be decoded by the circuit, pulling all the CS inputs low. This can easily be avoided by using a more definitive address decoding scheme. All the interrupts are ORed together to insure that all A/Ds have completed their conversion before the microprocessor is interrupted.

The subroutine, DATA IN, may be called from anywhere in the user's program. Once called, this routine initializes the

CPU, starts all the converters simultaneously and waits for the interrupt signal. Upon receiving the interrupt, it reads the converters (from HEX addresses 5000 through 5007) and stores the data successively at (arbitrarily chosen) HEX addresses 0200 to 0207, before returning to the user's program. All CPU registers then recover the original data they had before servicing DATA IN.

5.2 Auto-Zeroed Differential Transducer Amplifier and A/D Converter

The differential inputs of the ADC0801 series eliminate the need to perform a differential to single ended conversion for a differential transducer. Thus, one op amp can be eliminated since the differential to single ended conversion is provided by the differential input of the ADC0801 series. In general, a transducer preamp is required to take advantage of the full A/D converter input dynamic range.



TL/H/5671-26 FIGURE 16. Interfacing Multiple A/Ds in an MC6800 System SAMPLE PROGRAM FOR FIGURE 16 INTERFACING MULTIPLE A/Ds IN AN MC6800 SYSTEM **MNEMONICS** COMMENTS STX TEMP ; Save Contents of X LDX #\$002A ; Upon IRQ LOW CPU STX SFFF8 • Jumps to 0024

0012			DDA	##002A	, opon ma non or o
0015	FF FF F8		STX	\$FFF8	; Jumps to 002A
0018	B7 50 00		STAA	\$5000	;Starts all A/D's
001B	OE		CLI		
0010	3E		WAI		;Wait for interrupt
001D	CE 50 00		LDX	#\$5000	
0020	DF 40		STX	INDEXL	; Reset both INDEX
0022	CE 02 00		LDX	#\$0200	; 1 and 2 to starting
0025	DF 42		STX	INDEX2	; addresses
0027	DE 44		LDX	TEMP	
0029	39		RTS		; Return from subroutine
002A	DE 40	INTRPT	LDX	INDEX1	; INDEX1 \rightarrow X
0020	A6 00		LDAA	Х	; Read data in from A/D at X
002E	08		INX		; Increment X by one
002F	DF 40		STX	INDEX1	; $X \rightarrow INDEX1$
0031	DE 42		LDX	INDEX2	; INDEX2 \rightarrow X

ADDRESS

0010

0012

HEX CODE

DATAIN

DF 44

CE 00 2A

SAN	IPLE PROGRAM	FOR FIGURI	E 16 INTERP	ACING MUL	FIPLE A/Ds IN AN MC6800 SYSTEM
ADDRESS	HEX CODE		MNEMONIC	S	COMMENTS
0033	A7 00		STAA	х	; Store data at X
0035	80 02 07		CPX	#\$0207	; Have all A/D's been read?
0038	27 05		BEQ	RETURN	; Yes: branch to RETURN
003A	08		INX		; No: increment X by one
003B	DF 42		STX	INDEX2	$; x \rightarrow $ INDEX2
003D	20 EB		BRA	INTRPT	; Branch to 002A
003F	3B	RETURN	RTI		
0040	50 00	INDEX1	FDB	\$5000	; Starting address for A/D
0042	02 00	INDEX2	FDB	\$0200	; Starting address for data storage
0044	00 00	TEMP	FDB	\$0000	

Note 1: In order for the microprocessor to service subroutines and interrupts, the stack pointer must be dimensioned in the user's program.

For amplification of DC input signals, a major system error is the input offset voltage of the amplifiers used for the preamp. *Figure 17* is a gain of 100 differential preamp whose offset voltage errors will be cancelled by a zeroing subroutine which is performed by the INS8080A microprocessor system. The total allowable input offset voltage error for this preamp is only 50 μ V for 1/4 LSB error. This would obviously require very precise amplifiers. The expression for the differential output voltage of the preamp is:



where I_X is the current through resistor R_X. All of the offset error terms can be cancelled by making $\pm I_X R_X = V_{OS1} + V_{OS3} - V_{OS2}$. This is the principle of this auto-zeroing scheme.

The INS8080A uses the 3 I/O ports of an INS8255 Programable Peripheral Interface (PPI) to control the auto zeroing and input data from the ADC0801 as shown in *Figure 18*. The PPI is programmed for basic I/O operation (mode 0) with Port A being an input port and Ports B and C being output ports. Two bits of Port C are used to alternately open or close the 2 switches at the input of the preamp. Switch SW1 is closed to force the preamp's differential input to be zero during the zeroing subroutine and then opened and SW2 is then closed for conversion of the actual differential input signal. Using 2 switches in this manner eliminates concern for the ON resistance of the switches as they must conduct only the input bias current of the input amplifiers.

Output Port B is used as a successive approximation register by the 8080 and the binary scaled resistors in series with each output bit create a D/A converter. During the zeroing subroutine, the voltage at Vx increases or decreases as required to make the differential output voltage equal to zero. This is accomplished by ensuring that the voltage at the output of A1 is approximately 2.5V so that a logic "1" (5V) on any output of Port B will source current into node Vx thus raising the voltage at V_X and making the output differential more negative. Conversely, a logic "0" (0V) will pull current out of node V_X and decrease the voltage, causing the differential output to become more positive. For the resistor values shown, V_X can move ± 12 mV with a resolution of 50 μ V, which will null the offset error term to $\frac{1}{4}$ LSB of fullscale for the ADC0801. It is important that the voltage levels that drive the auto-zero resistors be constant. Also, for symmetry, a logic swing of 0V to 5V is convenient. To achieve this, a CMOS buffer is used for the logic output signals of Port B and this CMOS package is powered with a stable 5V source. Buffer amplifier A1 is necessary so that it can source or sink the D/A output current.



ADC0801/ADC0802/ADC0803/ADC0804/ADC0805

A flow chart for the zeroing subroutine is shown in *Figure* 19. It must be noted that the ADC0801 series will output an all zero code when it converts a negative input [V_{IN}(-) \geq V_{IN}(+)]. Also, a logic inversion exists as all of the I/O ports are buffered with inverting gates.

Basically, if the data read is zero, the differential output voltage is negative, so a bit in Port B is cleared to pull V_X more negative which will make the output more positive for the next conversion. If the data read is not zero, the output voltage is positive so a bit in Port B is set to make V_X more positive and the output more negative. This continues for 8 approximations and the differential output eventually converges to within 5 mV of zero.

The actual program is given in *Figure 20*. All addresses used are compatible with the BLC 80/10 microcomputer system. In particular:

Port A and the ADC0801 are at port address E4

Port B is at port address E5

Port C is at port address E6

PPI control word port is at port address E7

Program Counter automatically goes to ADDR:3C3D upon acknowledgement of an interrupt from the ADC0801

5.3 Multiple A/D Converters in a Z-80 Interrupt Driven Mode

In data acquisition systems where more than one A/D converter (or other peripheral device) will be interrupting program execution of a microprocessor, there is obviously a need for the CPU to determine which device requires servicing. *Figure 21* and the accompanying software is a method of determining which of 7 ADC0801 converters has completed a conversion (INTR asserted) and is requesting an interrupt. This circuit allows starting the A/D converters in any sequence, but will input and store valid data from the converters with a priority sequence of A/D 1 being read first, A/D 2 second, etc., through A/D 7 which would have the lowest priority for data being read. Only the converters whose INT is asserted will be read.

The key to decoding circuitry is the DM74LS373, 8-bit D type flip-flop. When the Z-80 acknowledges the interrupt, the program is vectored to a data input Z-80 subroutine. This subroutine will read a peripheral status word from the DM74LS373 which contains the logic state of the $\overline{\rm INTR}$ outputs of all the converters. Each converter which initiates an interrupt will place a logic "0" in a unique bit position in the status word and the subroutine will determine the identity of the converter and execute a data read. An identifier word (which indicates which A/D the data came from) is stored in the next sequential memory location above the location of the data so the program can keep track of the identity of the data entered.



FIGURE 19. Flow Chart for Auto-Zero Routine

7500						
3D00 3D02	3E90 D3E7	MVI 90 Out Control Port				
3D02 3D04	2601	MVIHO1	Aut 0-70	ro Subroutine	;Program	IFFL
3D04	2001 7C	MOVA,H	AUCU-DC	I O SUBIOUCINE		
3D07	D3E6	OUT C			: Close S	W1 open SW2
3D09	0680	MVI B 80				lize SAR bit pointer
3D0B	3E7F	MVIA7F				ize SAR code
3DOD	4 F	MOV C,A	Return			
3DOE	D3E5	OUT B			; Port B =	SAR code
3D10	31AA3D	LXI SP 3DAA	Start		;Dimensi	on stack pointer
3D13	D3E4	OUT A			; Start A	/D
3D15	FB	IE				
3D16	00	NOP	Loop		; Loop un	til INT asserted
3D17	C3163D	JMP Loop	A			
3D1A 3D1B	7A 0600	MOV A,D ADI 00	Auto-Ze	ro		
3D1B 3D1D	C600 CA2D3D	JZ Set C			• Tost 1 /	Dout nut data fan gana
3D1D 3D20	78	MOVA,B	Shift B		, IUSUAJ	D output data for zero
3D21	F600	ORI 00	SHITCD		;Clear c	arry
3D23	1F	RAR				l" in B right one place
3D24	FEOO	CPI 00				o? If yes last
3D26	CA373D	JZ Done				mation has been made
3D29	47	MOV B, A			• ••	
3D2A	C3333D	JMP New C				
3D2D	79	MOV A, C	Set C			
3D2E	BO	ORA B				in C that is in same
3D2F	4F	MOV C, A			;positio	on as "l" in B
3D30	C3203D	JMP Shift B				
3D33	A9	XRA C	New C			it in C that is in
3D34 3D37	C30D3D 47	JMP Return	Dama			sition as "1" in B
3D37 3D38	417 7C	MOV B,A MOV A,H	Done			tput new SAR code. 1, close SW2 then
3D39	EE03	XRI 03				l with program. Preamp
3D3B	D3E6	OUT C			; is now z	
3D3D	2020	•	Normal		,	
		•				
		•				
		Program for processing				
		proper data values				
3C3D	DBE4	INA	Read A/I	Subroutine	;ReadA/	
3C3F	EEFF	XRI FF			; Invert	data
3041	57	MOV D, A				0.0 7.0
3C42 3C43	78 E6FF	MOVA,B ANIFF				s=0? If not stay
3045	C21A3D	JNZ Auto-Zero			; in auto	zero Subroutine
3043	C33D3D	JMP Normal				
		re hexadecimal representations.				
		FIGURE 20. Softwa	are for Aut	o-Zeroed Differen	tial A/D	·
5.3 Multipl	e A/D Con	verters in a Z-80® Interrupt D	riven			
	Continued					
The followi	ng notes ap	oply:		5) The estimates	le of conce-	n are manned into 1/O oness
		ne CPU automatically performs a valid interrupt is acknowledged		with the follow		n are mapped into I/O space ignments:
		1). Hence, the subroutine startir		HEX PORT A	DDRESS	PERIPHERAL
dress of		,		00		MM74C374 8-bit flip-flop
		m the Z-80 and the data bus to	the 7-	01		A/D 1
		be inverted by bus drivers.		02		A/D 2
		ifying words will be stored in se	auen-	03		A/D 3
		is starting at the arbitrarily chose		04		A/D 4
drose X		is such as the arbitrarily offost		05		A/D 5

4) The stack pointer must be dimensioned in the main program as the RST 7 instruction automatically pushes the PC onto the stack and the subroutine uses an additional 6 stack addresses.

dress X 3E00.

A PORT ADDRESS	PERIPHERAL
00	MM74C374 8-bit flip-flop
01	A/D 1
02	A/D 2
03	A/D 3
04	A/D 4
05	A/D 5
06	A/D 6
07	A/D 7

This port address also serves as the A/D identifying word in the program.



FIGURE 21. Multiple A/Ds with Z-80 Type Microprocessor

			SOURCE	
LOC (OBJ CODE		STATEMENT	COMMENT
0038 E	E5		PUSH HL	; Save contents of all registers affected by
0039 0	05		PUSH BC	; this subroutine.
003A F	F5		PUSH AF	; Assumed INT mode 1 earlier set.
003B 2	21 00 3E		LD (HL),X3E00	; Initialize memory pointer where data will be stored.
003E 0	DE 01		LD C, XO1	; C register will be port ADDR of A/D converters.
0040 I	D300		OUT XOO, A	; Load peripheral status word into 8-bit latch.
0042 I	DBOO		INA, XOO	; Load status word into accumulator.
0044 4	47		LD B, A	; Save the status word.
0045 7	79	TEST	LD A, C	; Test to see if the status of all A/D's have
0046 F	FE 08		CP, X08	; been checked. If so, exit subroutine
0048 0	CA 60 00		JPZ, DONE	
004B 7	78		LDA,B	; Test a single bit in status word by looking for
004C 1	lF		RRA	; a "1" to be rotated into the CARRY (an INT
004D 4	47		LD B,A	; is loaded as a "l"). If CARRY is set then load
004E I	DA 5500		JPC, LOAD	; contents of A/D at port ADDR in C register.
	oc	NEXT	INC C	; If CARRY is not set, increment C register to point
0052 0	C3 4500		JP,TEST	; to next A/D, then test next bit in status word.
0055 B	ED 78	LOAD	INA, (C)	; Read data from interrupting A/D and invert
0057 B	ee ff		XOR FF	; the data.
	77		LD (HL),A	; Store the data
	20		INC L	
	71		LD (HL),C	; Store A/D identifier (A/D port ADDR) .
	20		INC L	
	C3 51 00		JP,NEXT	; Test next bit in status word.
	Fl	DONE	POP AF	; Re-establish all registers as they were
	Cl		POP BC	; before the interrupt.
	E1		POP HL	
0063 (C9		RET	;Return to original program

TEMP	PRANGE		0°C TO 70°C	0°C TO 70°C	0°C TO 70°C	-40°C TO +85°C
	$\pm \frac{1}{4}$					ADC0801LCN
RROR	Adjus	Bit	ADC0802LCWM	ADC0802LCV		ADC0802LCN
	± 1/2		ADC0803LCWM	ADC0803LCV		ADC0803LCN
	Adjus ±1B Unad		ADC0804LCWM	ADC0804LCV	ADC0804LCN	ADC0805LCN
PACKAG	L	<u> </u>	M20B-Small Outline	V20A—Chip Carrier	rier N20A—Molded DIP	
		Т	EMP RANGE	-40°C TO +85°C	-55°C TO + 125°C]
		ERROR	$\pm \frac{1}{4}$ Bit Adjusted $\pm \frac{1}{2}$ Bit Unadjusted $\pm \frac{1}{2}$ Bit Adjusted	ADC0801LCJ ADC0802LCJ ADC0803LCJ	ADC0801LJ ADC0802LJ	
		PAC	± 1Bit Unadjusted	ADC0804LCJ J20A—Cavity DIP	J20A—Cavity DIP	
		Diagrar ADC080X	± 1Bit Unadjusted CKAGE OUTLINE	ADC0804LCJ J20A—Cavity DIP	ADC080X	Package
		Diagrar ADC080X	± 1Bit Unadjusted CKAGE OUTLINE	ADC0804LCJ J20A—Cavity DIP	ADC080X ded Chip Carrier (PCC)	-
		Diagrar ADC080X	± 1Bit Unadjusted CKAGE OUTLINE INS ine (SO) Packages 20 - V _{CC} (OR V _{REF})	ADC0804LCJ J20A—Cavity DIP	ADC080X	-
	-Line and $\overline{CS} - 1$ $\overline{RD} - 2$	Diagrar ADC080X	± 1Bit Unadjusted CKAGE OUTLINE Ins ine (SO) Packages 20 - V _{CC} (OR V _{REF}) 19 - CLK R	ADC0804LCJ J20A—Cavity DIP Mol	ADC080X ded Chip Carrier (PCC) 을 표 절 원 원 년 1 년 1 1 1	
Dual-In•	-Line and $\overline{CS} - 1$ $\overline{RD} - 2$ $\overline{WR} - 3$	Diagrar ADC080X	± 1Bit Unadjusted CKAGE OUTLINE Ine (SO) Packages 20 - V _{CC} (OR V _{REF}) 19 - CLK R 18 - DB0 (LSB)	ADC0804LCJ J20A—Cavity DIP Mol	ADC080X ded Chip Carrier (PCC) 용 중 정 영 경 나 나 나 나 K R - 19	13 - DB5
Dual-In	-Line and CS - 1 RD - 2 WR - 3 CLK IN - 4	Diagrar ADC080X	± 1Bit Unadjusted CKAGE OUTLINE INS ine (SO) Packages 20 - V _{CC} (OR V _{REF}) 19 - CLK R 18 - DB0 (LSB) 17 - DB1	ADC0804LCJ J20A—Cavity DIP Mol V _{CC} (OR V _R	ADC080X ded Chip Carrier (PCC) 8 8 8 8 8 8 8 1 1 1 1 1 18 17 16 15 1 KR - 19 F) - 20	13 — D85 12 — D86
Dual-In -	-Line and CS - 1 RD - 2 WR - 3 LK IN - 4 INTR - 5	Diagrar ADC080X	± 1Bit Unadjusted CKAGE OUTLINE Ine (SO) Packages 20 - V _{CC} (OR V _{REF}) 19 - CLK R 18 - DB0 (LSB)	ADC0804LCJ J20A-Cavity DIP Mol V _{CC} (OR V _R	ADC080X ded Chip Carrier (PCC) 용 중 정 영 경 나 나 나 나 K R - 19	13 - DB5
Dual-In C	-Line and CS - 1 RD - 2 WR - 3 CLK IN - 4	Diagrar ADC080X	± 1Bit Unadjusted CKAGE OUTLINE INS ine (SO) Packages 20 - V _{CC} (OR V _{REF}) 19 - CLK R 18 - DB0 (LSB) 17 - DB1 16 - DB2	ADC0804LCJ J20A—Cavity DIP Mol V _{CC} (OR V _R	ADC080X ded Chip Carrier (PCC) 8 8 8 8 8 8 8 1 1 1 1 18 17 16 15 1 KR - 19 EF) - 20 CS - 1 RD - 2 WR - 3	$ \begin{array}{cccc} 13 & - DB5 \\ 12 & - DB6 \\ 11 & - DB7 (MSB) \\ 10 & - D GND \\ 9 & - V_{REF}/2 \end{array} $
Dual-In C V _I V	-Line and $\overline{CS} - 1$ $\overline{RD} - 2$ $\overline{WR} - 3$ LK IN - 4 $\overline{INTR} - 5$ IN(-) - 7 IN(-) - 7 IND - 8	Diagrar ADC080X	$\pm 1Bit Unadjusted$ CKAGE OUTLINE The (SO) Packages 20 - V _{CC} (OR V _{REF}) 19 - CLK R 18 - DB0 (LSB) 17 - DB1 16 - DB2 15 - DB3	ADC0804LCJ J20A—Cavity DIP Mol V _{CC} (OR V _R	ADC080X ded Chip Carrier (PCC) 8 8 8 8 8 8 8 1 1 1 1 18 17 16 15 1 KR - 19 F) - 20 CS - 1 RD - 2	13 DB5 12 DB6 11 DB7 (MSB) 10 D GND 9 V _{REF} /2
Dual-In C V, V A V _R	-Line and $\overrightarrow{CS} = 1$ $\overrightarrow{RD} = 2$ $\overrightarrow{WR} = 3$ \overrightarrow{LK} IN $\overrightarrow{R} = 5$ $\overrightarrow{W}(+) = 6$ $\overrightarrow{N}(-) = 7$	Diagrar ADC080X d Small Outli	± 1Bit Unadjusted CKAGE OUTLINE TS ine (SO) Packages 20 - V _{CC} (OR V _{REF}) 19 - CLK R 18 - DB0 (LSB) 17 - DB1 16 - DB2 15 - DB3 14 - DB4	ADC0804LCJ J20A—Cavity DIP Mol V _{CC} (OR V _R	ADC080X ded Chip Carrier (PCC) 8 8 8 8 8 8 8 1 1 1 1 18 17 16 15 1 KR - 19 EF) - 20 CS - 1 RD - 2 WR - 3	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$

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See Ordering Information

ADC0801/ADC0802/ADC0803/ADC0804/ADC0805

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